SN74LV86A-Q1 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATE

SCLS534C - AUGUST 2003 - REVISED APRIL 2008

Qualified for Automotive Applications

- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 2-V to 5.5-V V_{CC} Operation
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports

PW PACKAGE (TOP VIEW) 14 🛮 V_{CC} 1A [1B **∏** 2 13 AB 1Y **∏** 3 12**∏** 4A 11 🛮 4Y 2A | 2В [10**∏** 3B 2Y 🛮 9 🛮 3A 8 🛚 3Y GND L

description/ordering information

The SN74LV86A is a quadruple 2-input exclusive-OR gate designed for 2-V to 5.5-V V_{CC} operation.

This device contains four independent 2-input exclusive-OR gates. It performs the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

ORDERING INFORMATION[†]

| TA | PACK | \GE [‡] | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------|------------------|--------------------------|---------------------|
| -40°C to 105°C | TSSOP - PW | Tape and reel | SN74LV86ATPWRQ1 | LV86AT |

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE (each gate)

| INP | UTS | OUTPUT |
|-----|-----|--------|
| Α | В | Y |
| L | L | L |
| L | Н | Н |
| Н | L | Н |
| Н | Н | L |

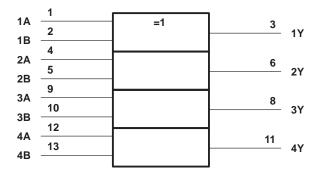


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

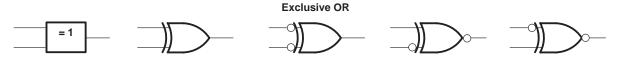
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

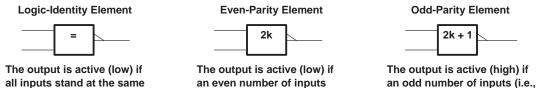
exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an 'LV86A gate in positive logic; negation can be shown at any two ports.

only 1 of the 2) are active.



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

(i.e., 0 or 2) are active.

| Supply voltage range, V _{CC} | 0.5 V to 7 V |
|------------------------------------------------------------|-------------------------------------------|
| Input voltage range, V _I (see Note 1) | 0.5 V to 7 V |
| Voltage range applied to any output in the high-impedance | |
| or power-off state, V _O (see Note 1) | 0.5 V to 7 V |
| Output voltage range, VO (see Notes 1 and 2) | \dots -0.5 V to V _{CC} + 0.5 V |
| Input clamp current, $I_{ K }(V_{ C } < 0)$ | –20 mA |
| Output clamp current, I _{OK} (V _O < 0) | –50 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ±25 mA |
| Continuous current through V _{CC} or GND | ±50 mA |
| Package thermal impedance, θ _{JA} (see Note 3) | 113°C/W |
| Storage temperature range, T _{stq} | –65°C to 150°C |

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.

logic level (i.e., A = B).

3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

| | | | MIN | MAX | UNIT | |
|----------|------------------------------------|--------------------------------------------|----------------------|---------------------|------|--|
| VCC | Supply voltage | | 2 | 5.5 | V | |
| | | V _{CC} = 2 V | 1.5 | | | |
| V | High level innerteeling | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | V _{CC} ×0.7 | | V | |
| V_{IH} | High-level input voltage | $V_{CC} = 3 \text{ V to } 3.6 \text{ V}$ | V _{CC} ×0.7 | | V | |
| | | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | V _{CC} ×0.7 | | | |
| | | V _{CC} = 2 V | | 0.5 | | |
| V | Lavy laval innyt valtage | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | | $V_{CC} \times 0.3$ | V | |
| V_{IL} | Low-level input voltage | $V_{CC} = 3 \text{ V to } 3.6 \text{ V}$ | | $V_{CC} \times 0.3$ | V | |
| | | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | | $V_{CC} \times 0.3$ | | |
| VI | Input voltage | | 0 | 5.5 | V | |
| VO | Output voltage | | 0 | Vcc | V | |
| | | V _{CC} = 2 V | | -50 | μΑ | |
| | | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | | -2 | | |
| ЮН | High-level output current | V _{CC} = 3 V to 3.6 V | | -6 | mA | |
| | | V _{CC} = 4.5 V to 5.5 V | | -12 | | |
| | | V _{CC} = 2 V | | 50 | μΑ | |
| | Level level entered entered | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | | 2 | | |
| loL | Low-level output current | V _{CC} = 3 V to 3.6 V | | 6 | mA | |
| | | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | | 12 | | |
| | | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 0 | 200 | | |
| Δt/Δν | Input transition rise or fall rate | V _{CC} = 3 V to 3.6 V | 0 | 100 | ns/V | |
| | | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | 0 | 20 | | |
| TA | Operating free-air temperature | | -40 | 105 | °C | |

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | VCC | MIN | TYP | MAX | UNIT |
|-----------|-------------------------------|--------|--------------|----------------------|-----|------|------|
| | I _{OH} = -50 μA | | 2 V to 5.5 V | V _{CC} -0.1 | | | |
| | I _{OH} = -2 mA | | 2.3 V | 2 | | | ., |
| VOH | I _{OH} = -6 mA | | 3 V | 2.48 | | | V |
| | I _{OH} = −12 mA | | 4.5 V | 3.8 | | | |
| | I _{OL} = 50 μA | | 2 V to 5.5 V | | | 0.1 | |
| | I _{OL} = 2 mA | | 2.3 V | | | 0.4 | V |
| VOL | I _{OL} = 6 mA | | 3 V | | | 0.44 | V |
| | I _{OL} = 12 mA | | 4.5 V | | | 0.55 | |
| IĮ | V _I = 5.5 V or GND | | 0 to 5.5 V | | | ±1 | μΑ |
| Icc | $V_I = V_{CC}$ or GND, | IO = 0 | 5.5 V | | | 20 | μΑ |
| loff | V_I or $V_O = 0$ to 5.5 V | | 0 | | | 5 | μΑ |
| Ci | $V_I = V_{CC}$ or GND | | 3.3 V | | 1.4 | | pF |

SN74LV86A-Q1 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATE

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

| DADAMETER | FROM | то | LOAD | T, | չ = 25°C | ; | | MAY | |
|-----------------|---------|----------|------------------------|-----|----------|------|-----|------|------|
| PARAMETER | (INPUT) | (OUTPUT) | CAPACITANCE | MIN | TYP | MAX | MIN | MAX | UNIT |
| t _{pd} | A or B | Υ | C _L = 50 pF | | 10.5 | 22.6 | 1 | 26.5 | ns |

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

| DADAMETED | FROM | FROM TO | | T, | չ = 25°C | ; | MIN | MAV | LINUT |
|-----------------|---------|----------|------------------------|-----|----------|------|-------|------|-------|
| PARAMETER | (INPUT) | (OUTPUT) | CAPACITANCE | MIN | TYP | MAX | IVIIN | MAX | UNIT |
| t _{pd} | A or B | Υ | C _L = 50 pF | | 7.4 | 14.5 | 1 | 16.5 | ns |

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

| DADAMETED | FROM | то | LOAD | T, | Վ = 25° C | ; | 84181 | MAY | LINUT |
|-----------------|---------|----------|------------------------|-----|------------------|-----|-------|-----|-------|
| PARAMETER | (INPUT) | (OUTPUT) | CAPACITANCE | MIN | TYP | MAX | MIN | MAX | UNIT |
| t _{pd} | A or B | Υ | C _L = 50 pF | | 5.3 | 8.8 | 1 | 10 | ns |

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

| | PARAMETER | MIN | TYP | MAX | UNIT |
|---------------------|-----------------------------------|------|------|------|------|
| VOL(P) | Quiet output, maximum dynamic VOL | | 0.2 | 0.8 | V |
| VOL(V) | Quiet output, minimum dynamic VOL | | -0.1 | -0.8 | V |
| VOH(V) | Quiet output, minimum dynamic VOH | | 3.1 | | V |
| V _{IH} (D) | High-level dynamic input voltage | 2.31 | | | V |
| V _{IL(D)} | Low-level dynamic input voltage | | | 0.99 | V |

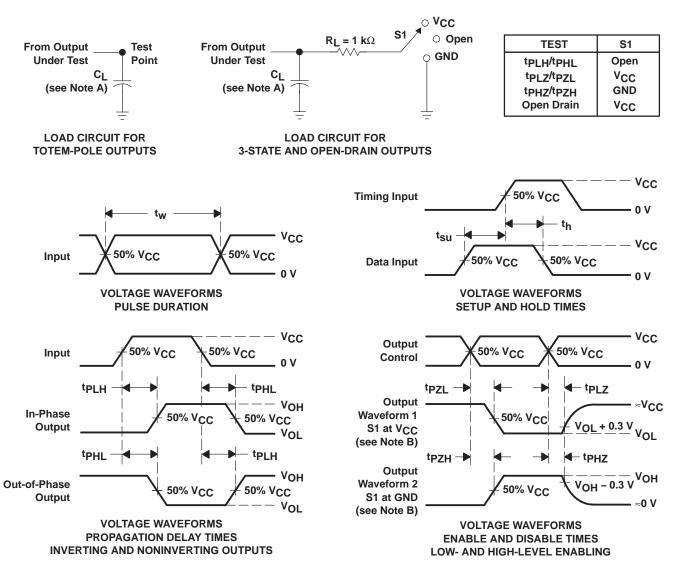
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

| | PARAMETER | TEST CONDITIONS | VCC | TYP | UNIT |
|-----------------|-------------------------------|--------------------------------------------|-------|-----|------|
| | Davies dissination constitues | C. 50 = 5 40 MHz | 3.3 V | 8.4 | |
| C _{pd} | Power dissipation capacitance | $C_L = 50 \text{ pF}, f = 10 \text{ MHz}$ | 5 V | 8.8 | pF |



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





10-Dec-2020

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|-------------------|--------|--------------|--------------------|------|----------------|--------------|-------------------------------|--------------------|--------------|-------------------------|---------|
| SN74LV86ATPWRG4Q1 | ACTIVE | TSSOP | PW | 14 | 2000 | RoHS & Green | (-) | Level-1-260C-UNLIM | -40 to 105 | LV86AT | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LV86A-Q1:



PACKAGE OPTION ADDENDUM

10-Dec-2020

Enhanced Product: SN74LV86A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|-----------------------------------------------------------|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | U | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------------|-------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN74LV86ATPWRG4Q1 | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|-------------------|--------------|-----------------|------|------|-------------|------------|-------------|--|
| SN74LV86ATPWRG4Q1 | TSSOP | PW | 14 | 2000 | 356.0 | 356.0 | 35.0 | |

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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